

HEATSINK DEVICE AND METHOD

Abstract

5 A method and device for thermal conduction is provided. Devices and methods are shown that include the ability to dissipate increased amounts of heat due to the use of an active heat transfer device. Devices and methods are shown that share the necessary heat transfer between a passive heat transfer device and an active heat transfer device, thus increasing the amount of heat dissipated while maintaining reliability of the individual components. Devices and methods are shown that
10 include an increased length of the heatsink which can keep large temperature differences between heat transfer structures and the heat transfer fluid such as air.

"Express Mail" mailing label number: EV332571651US

Date of Deposit: September 30, 2003

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